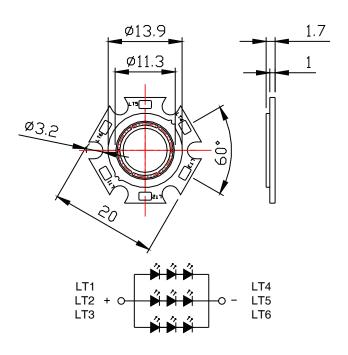




#### Package Dimensions:



All dimensions are in mm Tolerance: ±0.25mm

#### Features:

- Pb-Free soldering application
- Multi-Chip package
- · High reliability

### **Applications:**

- Bulb
- · Indoor decoration lighting
- · Signal and symbol luminaries
- Reading lights
- Portable flashlight

### Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation*	Po	1,260	mW
LED Junction Temperature*	Tj	120	V
Reverse Voltage*	Vr	5	mA
D.C. Forward Current*	lr	350	μΑ
Peak Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)*	If (Peak)	1,000	mA
Storage Temperature Range	Tstg.	-40 to +85	°C
Soldering Temperature (1.6mm from body)	Tsld.	Dip Soldering: 260°C for 10sec. Hand Soldering: 350°C for 3sec.	
Electric Static Discharge Threshold (HBM)*	ESD	300	V

<sup>\*</sup> The values are based on 1 die performance.





### **Electrical & Optical Characteristics**

Parameter		Symbol	Condition	Min.	Тур.	Max.	Unit
				250	300		
Luminous Flux	Rank L1	Ф٧	IF=1,050mA	250		300	lm
	Rank L2			300		350	
					6.5		
Forward Voltage	Rank V1	VF	IF=1,050m	6		6.5	V
	Rank V2			5.51		7	
Correlated Colour Temperature		CCT	IF=1,050mA	2,875	3,000		K
CIE Chromaticity Coordinates: X Axis		Х	IF=1,050mA		0.4338		
CIE Chromaticity Coordinates: Y Axis		Y	IF=1,050mA		0.4030		
Reverse Current		lr	Vr=5V			50	μA
Colour Rendering Index		CRI	IF=1,050mA		74		Ra
Viewing Angle at 50%			2θ½		120		Deg
Thermal Resistance Junction to	o Case		Rθj-c		15		°C / W

Notes: 1. The data is tested by IS tester.

2. Customer's special requirements are also welcome.

#### Typical Electrical & Optical Characteristics Curves:

(25°C Ambient temperature unless otherwise noted)

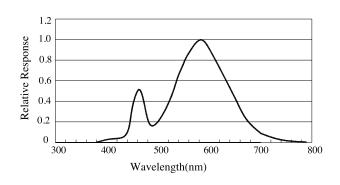
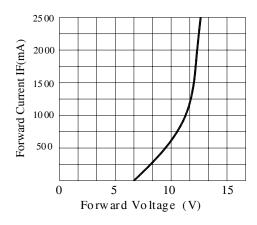
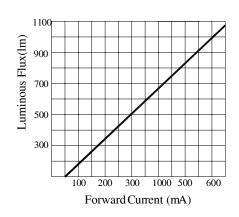


Fig.1 WARM WHITE LED Spectrum VS. WAVELENGTH

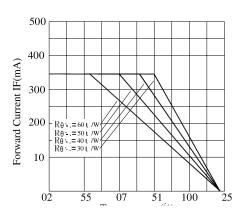


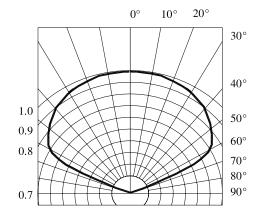




Forward Current VS. Applied Voltage

Forward Current VS. Luminous Flux





Ambient Temperature VS. Forward Current

Radiation Diagram

### **Chromaticity Coordinates Specifications for Bin Grading:**

Bin	Rank				
7A	Х	0.4147	0.4221	0.4342	0.4259
	Υ	0.3814	0.3984	0.4028	0.3853
7B	Х	0.4221	0.4299	0.4430	0.4342
	Υ	0.3984	0.4165	0.4212	0.4028
7C	Х	0.4342	0.4430	0.4562	0.4465
	Y	0.4028	0.4212	0.4260	0.4071
7D	Х	0.4259	0.4342	0.4465	0.4373
	Υ	0.3853	0.4028	0.4071	0.3893

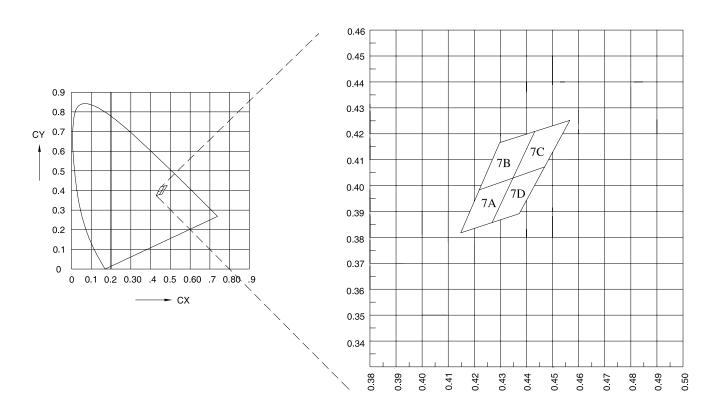
Note: X. Y

Tolerance each Bin limit is ±0.01





### **Chromaticity Coordinates & Bin Grading Diagram:**



#### **Part Number Table**

LED Chip		Lens Colour	Part Number
Material	Colour Coordinates		
InGaN/Sapphire	Warm white	Yellow diffused	703-0117

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